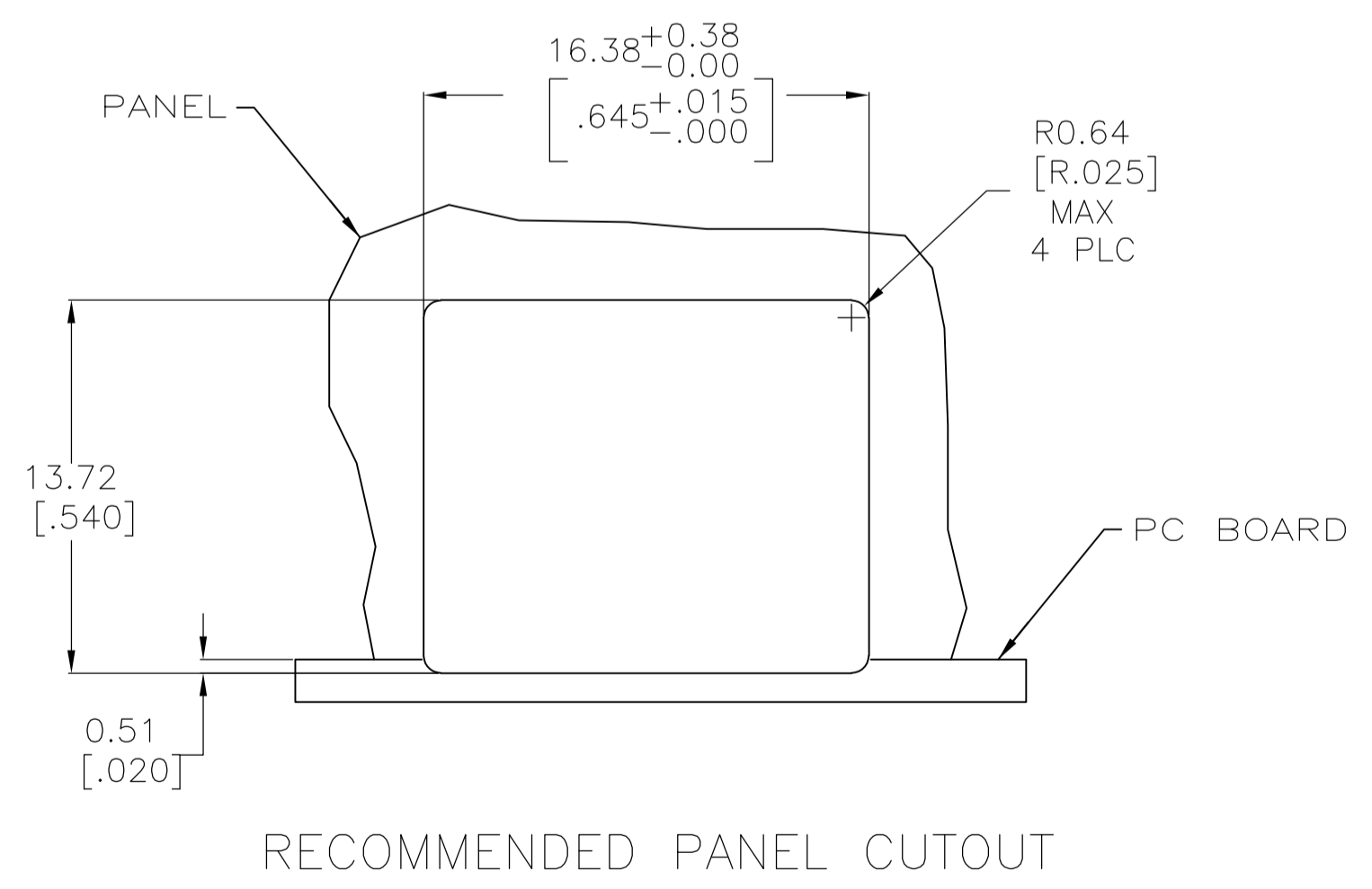
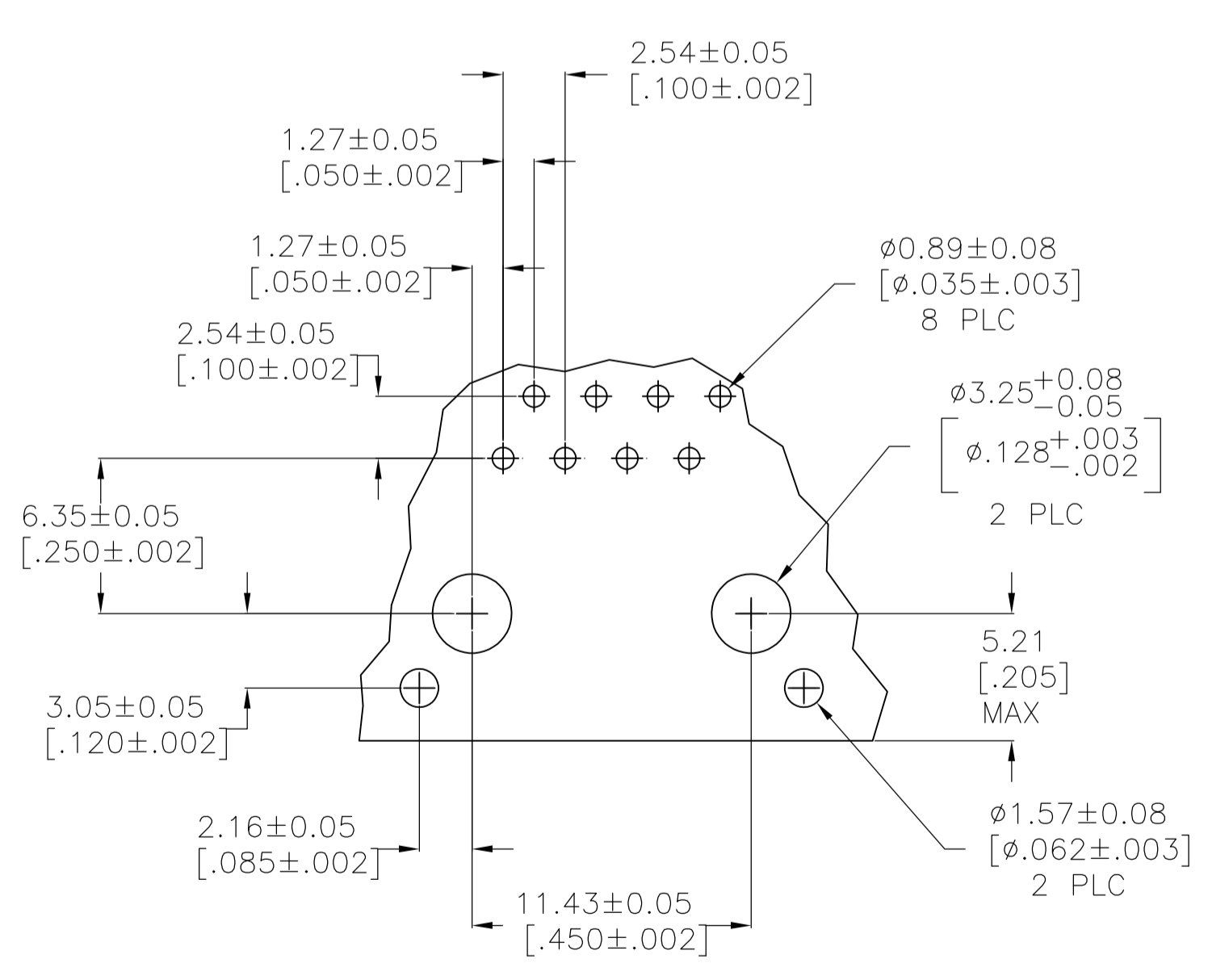
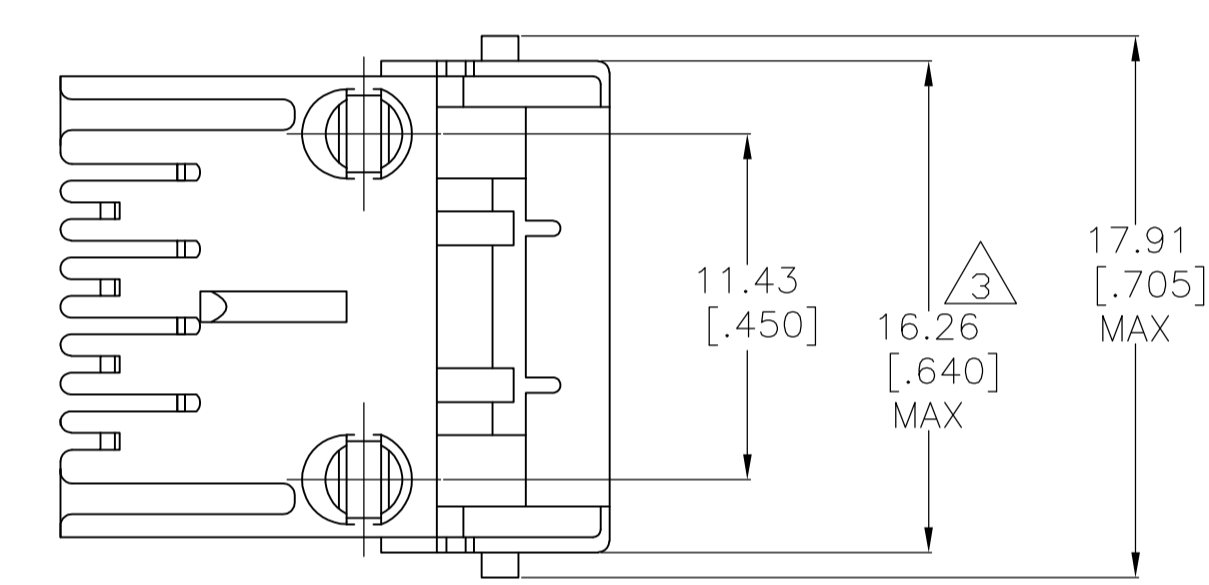
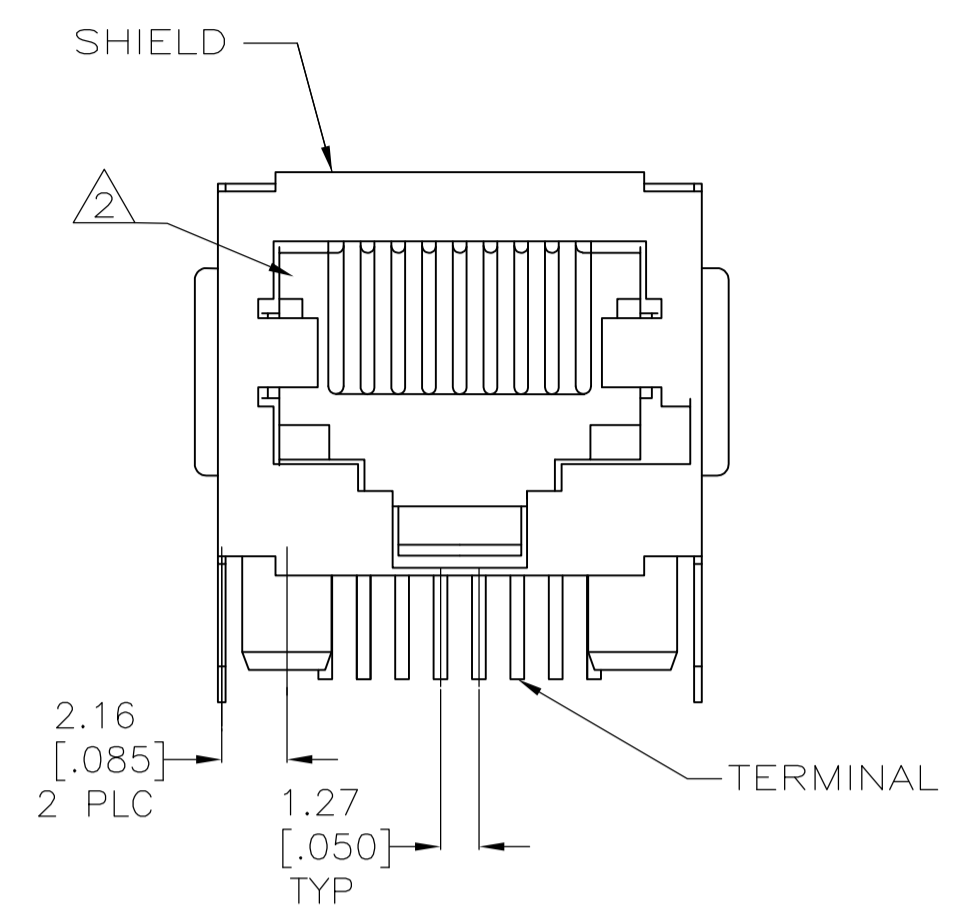
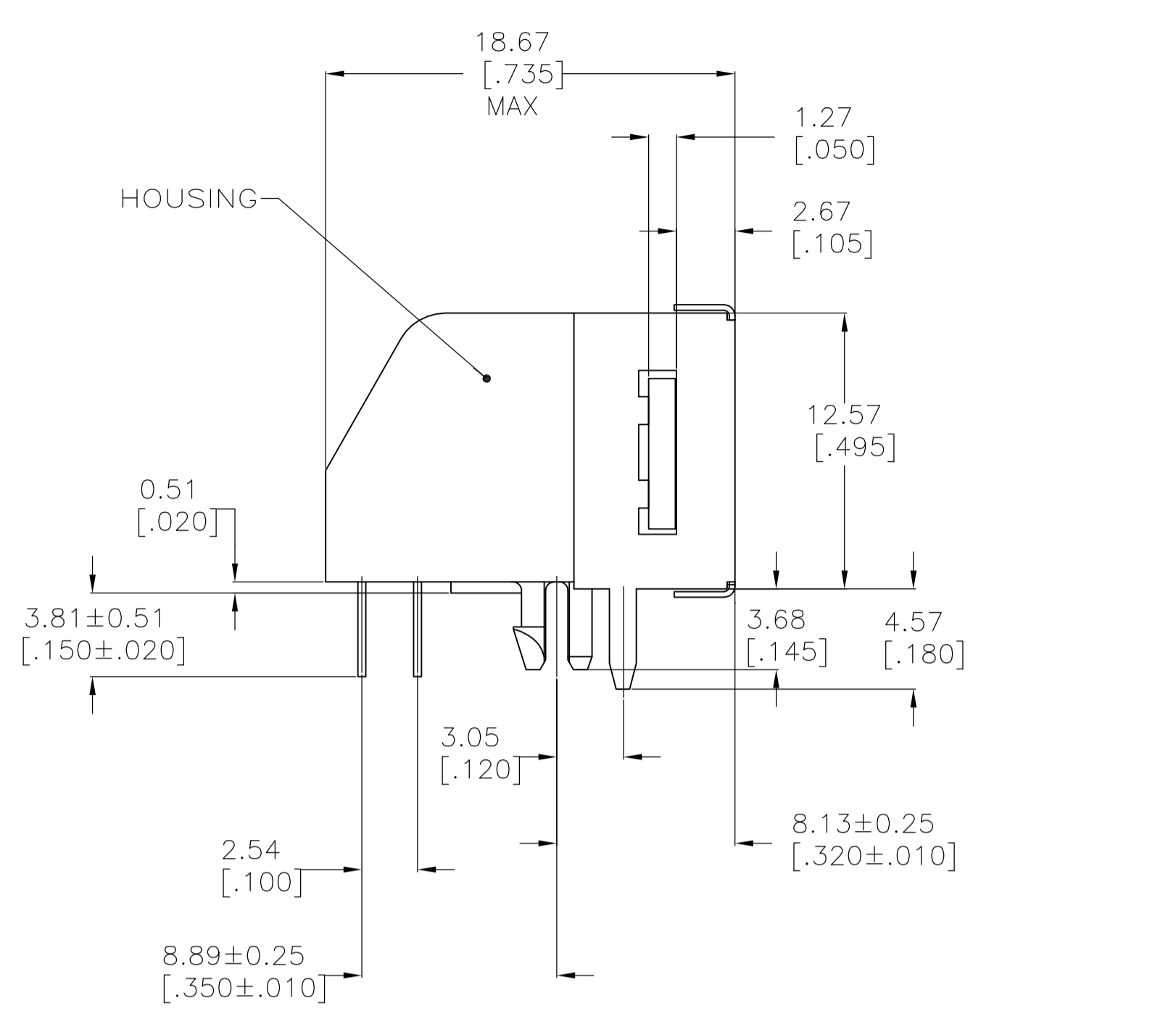


LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DN	APVD		
C1		REVISED PER ECO-11-005033	24MAR11	RK	HMR		



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)

RECOMMENDED PANEL CUTOUT

1. MATERIAL:
 HOUSING - PBT POLYESTER, COLOR: BLACK
 TERMINAL - 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27µm [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm [.000150] THICK MATTE TIN IN SOLDER AREA OVER 1.27µm [.000050] THICK NICKEL UNDERPLATE
 SHIELD - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 3.0µm [.000120] MINIMUM THICK REFLOWED TIN
2. CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
3. DIMENSIONS MEASURED ALONG FRONT EDGES OF MATING FACE

5556591-1
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN: G.A./L.A.MAYER 07NOV2007 CHK: P.RECCE 05NOV2007 APVD: S.FLICKINGER 05NOV2007	STE TE Connectivity	
DIMENSIONS: mm [INCHES] TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± - 1 PLC ± - 2 PLC ± 0.13[.005] 3 PLC ± - 4 PLC ± - ANGLES ± -		NAME: MODULAR JACK ASSEMBLY, SHIELDED KEYED, 8 POSITION, LOW PROFILE, RIGHT ANGLE, PANEL GROUND WITH PANEL STOPS PRODUCT SPEC: 108-1163 APPLICATION SPEC: 114-2048	SIZE: A1 CAGE CODE: 00779 DRAWING NO: 5556591	RESTRICTED TO: - SCALE: 4:1 SHEET: 1 OF 1 REV: C1
MATERIAL: SEE NOTE 1		FINISH: SEE NOTE 1		CUSTOMER DRAWING

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)